IN THE CLAIMS:

Please amend claims 1-11, and add new claims 12-20 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Currently Amended) An Internet thermal data analysis system comprising:

~~an~~ a user end interface to ~~retrieved~~ retrieve requests of package parameters from ~~the~~ a far-end user ~~who need~~ requesting thermal package analysis via a network;

a storage media;

a job database containing several job forms and providing at least one of said job forms for the far-end user to input said package parameters;

a thermal analysis module containing at least one application software to analyze said package parameters;

a package parameter database having package related data stored therein;

a process unit access package parameters, said package related data and executing said application software, so as to generate a thermal data simulation report based on said package data; and

a file transfer software responsive to thermal data simulation report and ~~forward~~ forwarding said thermal data simulation report to said far-end user.

Claim 2. (Currently Amended) The system of claim 1, wherein said thermal data simulation report ~~includesθja~~ includes θja = {Tj-Ta}/P, wherein said θja is a temperature variance from a junction temperature to an ambient temperature per unit power dissipation, said Tj indicates the junction temperature, said Ta ~~is~~ indicates the ambient temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~4~~ 3. (Currently Amended) The system of claim 1, wherein said thermal data simulation report includes Ψjt = (Tj-Tt)/P, wherein said Ψjt is a temperature variance from a junction temperature to a package top center temperature per unit power dissipation, said Tt indicates the package top center temperature, said Tj indicates the junction temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~5~~ 4. (Currently Amended) The system of claim 1, wherein said thermal data simulation report includes θjc = (Tj-Tc)/P, wherein said θjc is a temperature variance from a junction temperature to a case temperature per unit power dissipation, said Tc indicates the case temperature, said Tj indicates the junction temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~6~~ 5. (Currently Amended) The system of claim 1, wherein said thermal data simulation report includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top.

Claim ~~7~~ 6. (Currently Amended) A method for automatically providing thermal data of a semiconductor package comprising the steps of:

inputting parameters that relates to a semiconductor package by a user;

recording said parameters in a job database;

retrieving an information from said job database;

analyzing a thermal data of a package based on said parameters sent by said user;

generating a thermal data simulation report; and

forwarding said thermal data simulation report to said user through a network.

Claim ~~8~~ 7. (Currently Amended) The method of claim ~~7~~ 6, wherein said thermal data simulation is analyzed by a thermal analysis module.

Claim ~~9~~ 8. (Currently Amended) The method of claim ~~7~~ 6, wherein said thermal data simulation report includes θja =(Tj-Ta)/P, ~~wherein~~ said θja is a temperature variance from a junction temperature to an ambient temperature per unit power dissipation, said Tj indicates the junction temperature, said Ta is the ambient temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~10~~ 9. (Currently Amended) The method of claim ~~7~~ 6, wherein said thermal data simulation report includes Ψjt=(Tj-Tt)/P, wherein said Ψjt is a temperature variance from a junction temperature to a package top center temperature per unit power dissipation, said Tt indicates the package top center temperature, said Tj indicates the junction temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~11~~ 10. (Currently Amended) The method of claim ~~7~~ 6, wherein said thermal data simulation report includes θjc=(Tj-Tc)/P, wherein said θjc is a temperature variance from a junction temperature to a case temperature per unit power dissipation, said Tc indicates the case temperature, said Tj indicates the junction temperature and ~~wherein~~ said P indicates the power dissipation.

Claim ~~12~~ 11. (Currently Amended) The method of claim ~~7~~ 6, wherein said thermal data simulation report includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top.

Claim 12. (New) An Internet thermal data analysis system comprising:

an user end interface to retrieve requests of package parameters from a far-end user requesting thermal package analysis via a network;

a storage media;

a job database containing several job forms and providing at least one of said job forms for the far-end user to input said package parameters;

a thermal analysis module containing at least one application software to analyze said package parameters;

a package parameter database having package related data stored therein;

a process unit access package parameters, said package related data and executing said application software, so as to generate a thermal data simulation report based on said package data, said thermal data simulation report includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top; and

a file transfer software responsive to said thermal data simulation report and forwarding said thermal data simulation to said far-end user.

Claim 13. (New) The system of claim 12, wherein said thermal data simulation report includes $\theta ja = \{Tj-Ta\}/P$, wherein said θja is a temperature variance from a junction temperature to an ambient temperature per unit power dissipation, said Tj indicates the junction temperature, said Ta indicates the ambient temperature and said P indicates the power dissipation.

Claim 14. (New) The system of claim 13, wherein said thermal data simulation report includes $\Psi jt = (Tj-Tt)/P$, wherein said Ψjt is a temperature variance from a junction temperature to a package top center temperature per unit power dissipation, said Tt indicates the package top center temperature, said Tj indicates the junction temperature and said P indicates the power dissipation.

Claim 15. (New) The system of claim 1, wherein said thermal data simulation report includes $\theta jc = (Tj-Tc)/P$, wherein said θjc is a temperature variance from a junction temperature to a case temperature per unit power dissipation, said Tc indicates the case temperature, said Tj indicates the junction temperature and said P indicates the power dissipation.

Claim 16. (New) A method for automatically providing thermal data of a semiconductor package comprising the steps of:

inputting parameters that relates to a semiconductor package by a user;

recording said parameters in a job database;

retrieving an information from said job database;

analyzing a thermal data of a package based on said parameters sent by said user;

generating a thermal data simulation report, said thermal data simulation report includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top; and

forwarding said thermal data simulation report to said user through a network.

Claim 17. (New) The method of claim 16, wherein said thermal data simulation is analyzed by a thermal analysis module.

Claim 18. (New) The method of claim 16, wherein said thermal data simulation report includes $\theta ja = (Tj-Ta)/P$, wherein said θja is a temperature variance from a junction temperature to an ambient temperature per unit power dissipation, said Tj indicates the junction temperature, said Ta is the ambient temperature and said P indicates the power dissipation.

Claim 19. (New) The method of claim 16, wherein said thermal data simulation report includes $\Psi jt=(Tj-Tt)/P$, wherein said Ψjt is a temperature variance from a junction temperature to a package top center temperature per unit power dissipation, said Tt indicates the package top center temperature, said Tj indicates the junction temperature and said P indicates the power dissipation.

Claim 20. (New) The method of claim 16, wherein said thermal data simulation report includes $\theta jc=(Tj-Tc)/P$, wherein said θjc is a temperature variance from a junction temperature to a case temperature per unit power dissipation, said Tc indicates the case temperature, said Tj indicates the junction temperature and said P indicates the power dissipation.